- 1 1. A method comprising:
 2 forming a protective coating on an exposed
 3 surface of an electronic device, including forming the
 4 protective coating on a conductive termination connected to
 5 a circuit element in the electronic device; and
 6 making a window in the protective coating to
 7 expose the termination.
- 1 2. The method of claim 1 wherein the coating is uniform in thickness.
- 1 3. The method of claim 1 wherein the coating 2 conforms to the geometric configuration of the electronic 3 device.
- 1 4. The method of claim 1 wherein coating the 2 electronic device comprises vapor deposition.
- 1 5. The method of claim 1 wherein the protective 2 layer comprises a polymer.
- 1 6. The method of claim 5 wherein the polymer 2 comprises poly-para-xylylene.
- 7. The method of claim 1 wherein the electronic device comprises an integrated power device (IPD).
- 1 8. The method of claim 1 wherein the circuit 2 element comprises a semiconductor.
- 1 9. The method of claim 1 wherein the circuit 2 element comprises a power semiconductor.

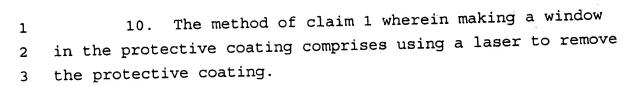
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- The method of claim 10 wherein the laser comprises a stroke marking laser.
- The method of claim 10 wherein the laser 12. comprises a mask marking laser.
- The method of claim 10 wherein the laser 13. comprises a fixed-beam laser. 2
- The method of claim 10 wherein making a window 14. 1 in the protective coating comprises using a predetermined 2 pattern. 3
- The method of claim 14 wherein the 1 predetermined pattern comprises a pattern of parallel 2 strokes for removing strips of the protective coating. 3
- The method of claim 1 wherein making a window 1 in the protective coating comprises making a perimeter cut 2 with a laser to outline the area of the protective coating 3 to be removed and removing the outlined area of the 4 protective coating. 5
- The method of claim 16 wherein removing the 17. 1. outlined area of protective coating comprises peeling the 2 protective coating away from the surface of the electronic 3 device. 4

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2 material comprises polyurea.

1 18. The method of claim 17 wherein peeling the 2 protective coating comprises passing a gas over the surface 3 of the protective coating until the protective coating 4 dislodges from the electronic device.
19. The method of claim 18 wherein the gas comprises compressed air.
20. The method of claim 18 wherein the gas comprises an inert gas.
1 21. The method of claim 1 further comprising: 2 applying solder to the portion of the 3 conductive termination exposed by the window in the
4 protective coating.
1 22. The method of claim 21 wherein applying solder 2 comprises reflow soldering.
1 23. The method of claim 1 further comprising: 2 encapsulating the electronic device in a 3 potting material.
24. The method of claim 23 wherein the potting material comprises a silicone resin.

The method of claim 23 wherein the potting

	and a mathed gemprising:
1	26. A method comprising: forming a protective coating of poly-para-
2	forming a protective coating of poly
3	xylylene on an exposed surface of an integrated power
4	device, including forming the protective coating on a
5	conductive termination connected to a semiconductor in the
6	power device; and
7	cutting a window in the protective coating
8	using a laser to expose the termination.
1	27. A method comprising: forming a protective coating on an exposed
2	forming a protective coating on an exposed
3	surface of an electronic device, including forming the
4	protective coating on a conductive termination connected to
5	a circuit element in the electronic device;
6	making a window in the protective coating to
7	expose the termination;
8	applying solder to the portion of the
9	conductive termination exposed by the window in the
10	protective coating; and
11	encapsulating the electronic device in a
12	potting material.
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1	28. A method for use with an electronic device having a conductive termination pad and an electronic
2	having a conductive termination pad and an electronic
3	component connected to the pad, the method comprising:
4	applying a protective coating to surfaces of
5	the termination pad and the electronic component;
5 6	the protective coating to
7	and and
8	calling rolder into the window to make
	between the solder pad and a circuit.
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1	29. A circuit comprising:	
2	a circuit board;	
3	an electronic device comprising	
4	a substrate,	
5 .	a conductive termination pad formed on the	
6	substrate,	
7	an electronic component mounted on the	
8	substrate and connected to the termination pad,	
9	a protective coating on the pad and the	
10	electronic component, and	
11	a window formed in the protective coating	
12	to expose the conductive termination pad; and	
13	solder connecting the termination pad to the	
. 14	4 circuit board via the window.	
1	30. An apparatus comprising: an electronic device;	
2		
. 3	a protective, conformal coating on the surface	
4	of the electronic device containing conductive terminations;	
5	and .	
6	a window in the protective coating to expose	
7	the conductive terminations.	

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